ALPHA & OMEGA SEMICONDUCTOR

AOD4184/AOI4184

40V N-Channel MOSFET

General Description

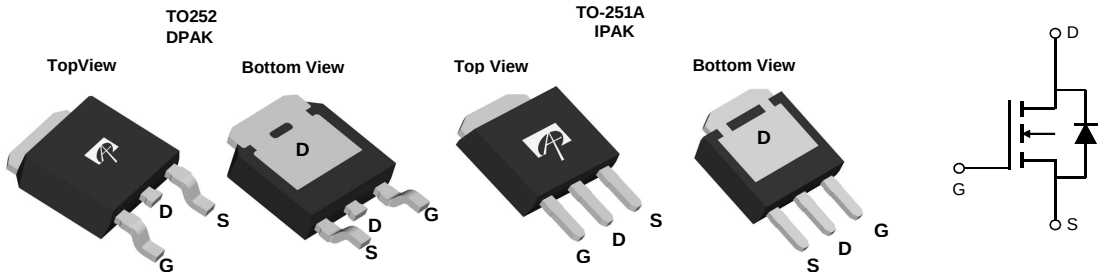
The AOD4184/AOI4184 used advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. With the excellent thermal resistance of the DPAK package, those devices are well suited for high current load applications.

Product Summary

V_{DS}	40V
I_D (at V_{GS}=10V)	50A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 8mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 11mΩ

100% UIS Tested
100% R_g Tested

Green Product



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [G]	T_C=25°C	I_D	50	A
	T_C=100°C		40	
Pulsed Drain Current [C]		I_{DM}	120	
Continuous Drain Current	T_A=25°C	I_{DSM}	12	A
	T_A=70°C		9.5	
Avalanche Current [C]		I_{AS}, I_{AR}	35	A
Avalanche energy L=0.1mH [C]		E_{AS}, E_{AR}	61	mJ
Power Dissipation [B]	T_C=25°C	P_D	50	W
	T_C=100°C		25	
Power Dissipation [A]	T_A=25°C	P_{DSM}	2.3	W
	T_A=70°C		1.5	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	18	22	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		44	55	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	2.4	3	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=40V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1.7	2.2	2.6	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	120			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A		6.7	8	mΩ
		T_J=125°C		11	13	
		V_{GS}=4.5V, I_D=15A		8.5	11	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A		37		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.72	1	V
I_S	Maximum Body-Diode Continuous Current				20	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=20V, f=1MHz	1200	1500	1800	pF
C_{oss}	Output Capacitance		150	215	280	pF
C_{rss}	Reverse Transfer Capacitance		80	135	190	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	2	3.5	5	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=20V, I_D=20A	21	27.2	33	nC
Q_g(4.5V)	Total Gate Charge		10	13.6	16	nC
Q_{gs}	Gate Source Charge			4.5		nC
Q_{gd}	Gate Drain Charge			6.4		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=20V, R_L=1Ω, R_{GEN}=3Ω		6.4		ns
t_r	Turn-On Rise Time			17.2		ns
$t_{D(off)}$	Turn-Off DelayTime			29.6		ns
t_f	Turn-Off Fall Time			16.8		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=100A/µs	20	29	38	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, dI/dt=100A/µs	18	26	34	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
B. The power dissipation P_D is based on $T_{J(MAX)}$=175° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175° C. Ratings are based on low frequency and duty cycles to keep initial T_J =25° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

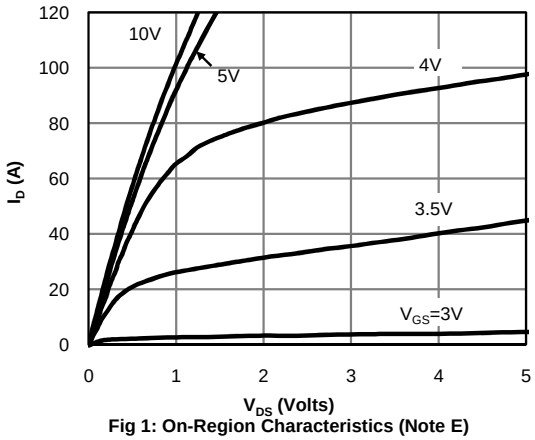


Fig 1: On-Region Characteristics (Note E)

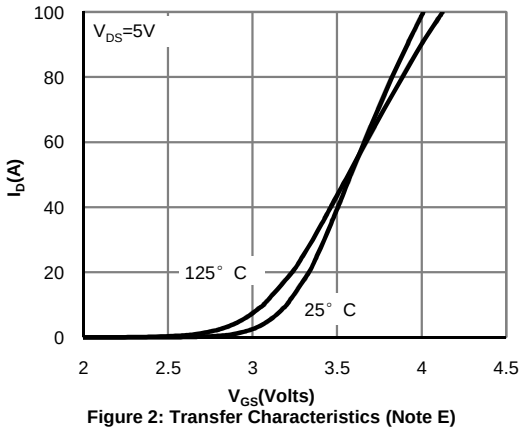


Figure 2: Transfer Characteristics (Note E)

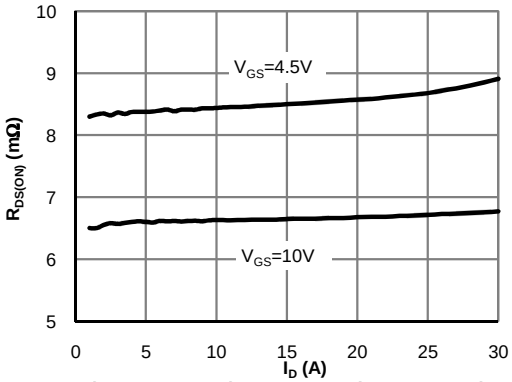


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

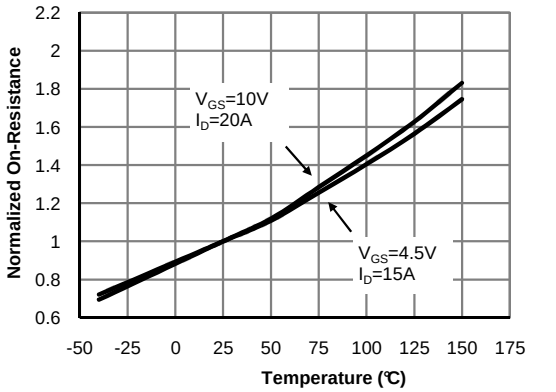


Figure 4: On-Resistance vs. Junction Temperature (Note E)

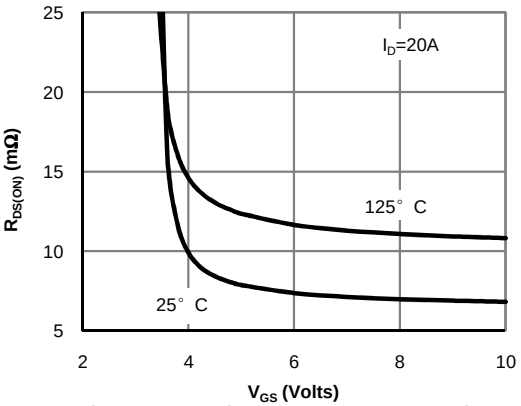


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

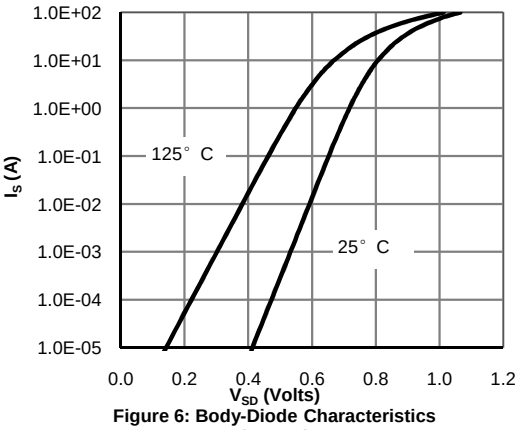


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

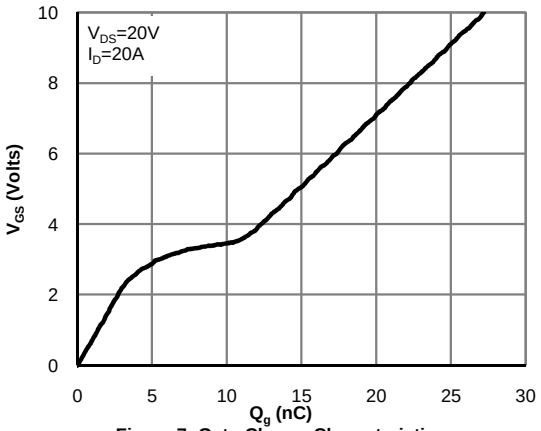


Figure 7: Gate-Charge Characteristics

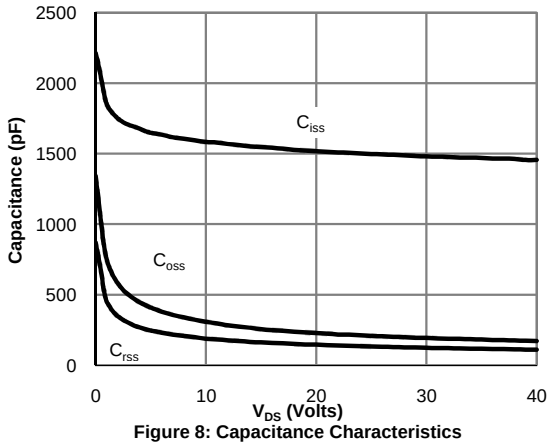


Figure 8: Capacitance Characteristics

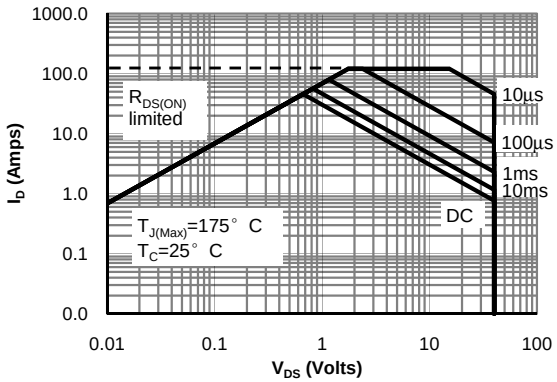


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

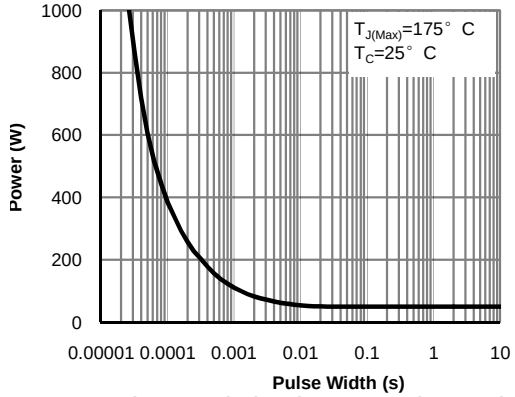


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

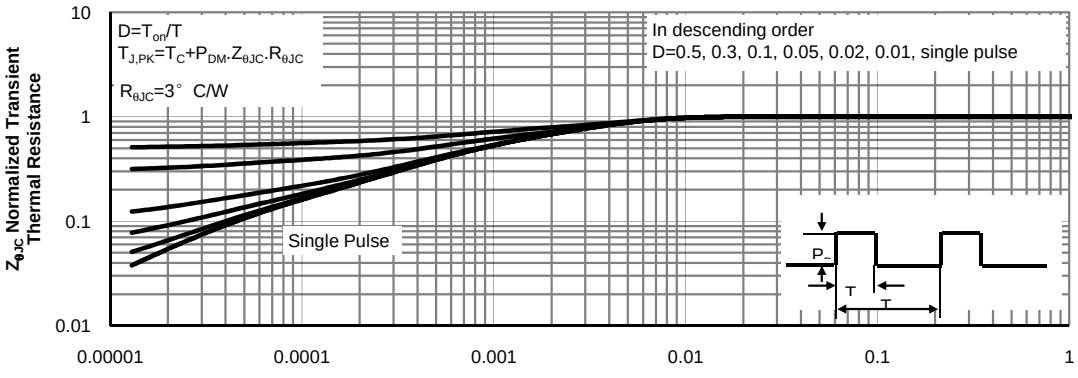


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

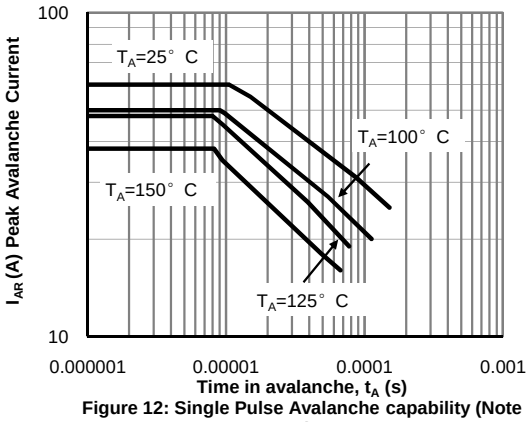


Figure 12: Single Pulse Avalanche capability (Note C)

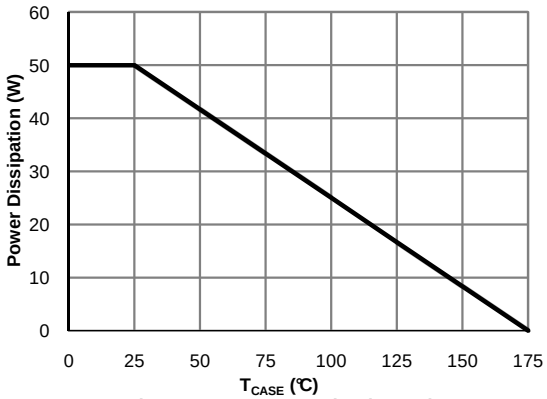


Figure 13: Power De-rating (Note F)

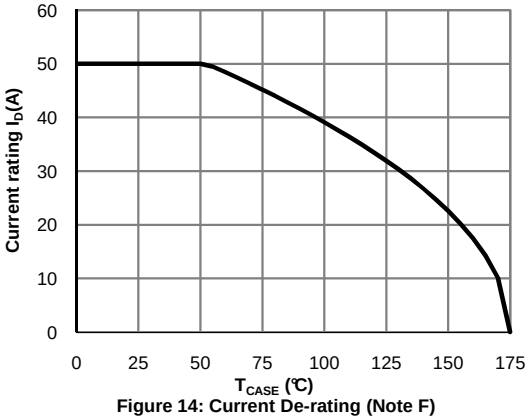


Figure 14: Current De-rating (Note F)

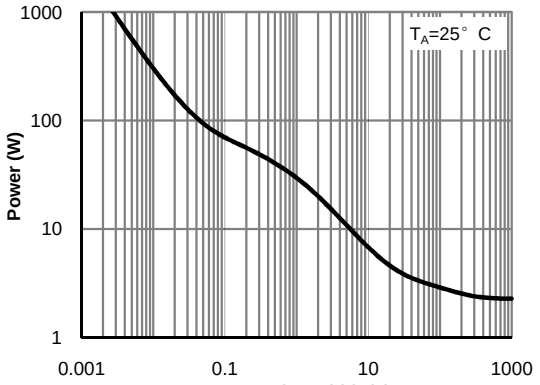


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

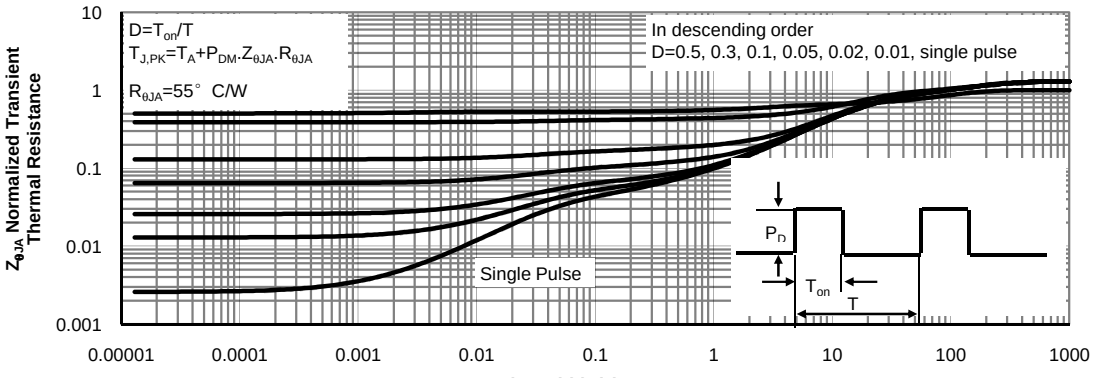
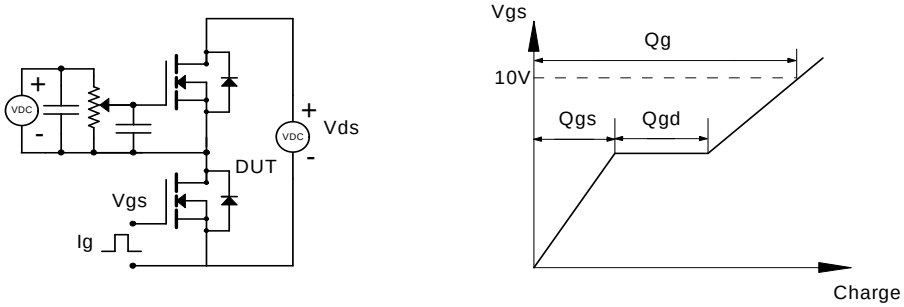
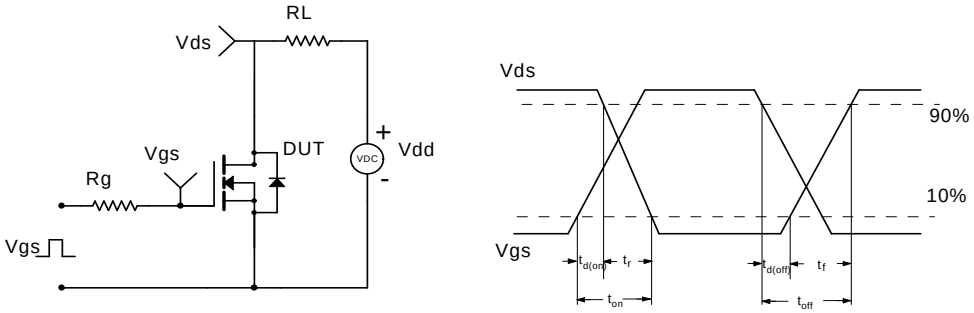


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

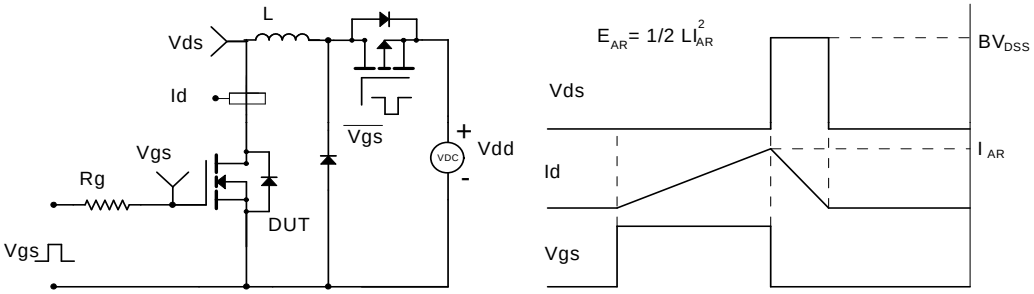
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms